MIL-PRF-38535.

UNDERCOATING 100 TO 350 MICROINCHES THICK PER TO 225 MICROINCHES THICK OVER ELECTROPLATED NICKEL ONLY.

ALLOWED. MAY BE CONNECTED TO VSS FOR PLATING OPTIONAL.

NOTES:

2. ALL EXPOSED METAL AREAS MUST BE GOLD PLATED 100

1. PACKAGE MATERIAL: OPAQUE 90% MINIMUM ALUMINA CERAMIC.

4. SEE UTMC SPEC. 40-7150-XX FOR FURTHER REQUIREMENTS.

3. THE SEAL RING MUST BE ELECTRICALLY CONNECTED TO VSS.

5. PIN 1 ID MUST BE GOLD PLATED. NO ALPHANUMERIC FIGURES

6. BONDFINGER NUMBERS, LETTERS, AND I.D. ARE FOR REFERENCE ONLY.

DESIGN NOTES:

1. DRAWING UNITS ARE IN MILS

2. PACKAGE OUTLINE IS 21X21MM

3. DIE SIZE IS 446 MILS SQUARE

4. DIE BOND PAD PITCH IS 3.78 UM MIN

5. STANDARD ROUTING TRACE WIDTH IS ~4 MILS

6. VIA SIZES ARE 4 MILS AND 8 MILS

7. LGA PAD/OPENING SIZE IS 31.5 MILS

8. LAYOUT WILL REQUIRE LENGTH MATCHING AND CONTROLLED IMPEDANCE TRACES.

9. ROUTING AND STACK-UP PLANS WILL BE PROVIDED.

10. CONNECT FIDUCIALS TO VSS.

11. TYPICAL BONDFINGERS ARE 4 MILS WIDE, 3.56 MILS GAP.